SOT1677-1

HVQFN12, plastic, thermal enhanced very thin quad flatpack; no leads; 12 terminals; 0.5 mm pitch; 3 mm x 3 mm x 0.85 mm body

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN12
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	11-6-2017
Manufacturer package code	98ASA00227D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	3	-	mm
E	package width		-	-	3	-	mm
A_2	package height		-	-	0.85	-	mm
e	nominal pitch		-	-	0.5	-	mm
n_2	actual quantity of termination		-	-	12	-	A/A

2. Package outline

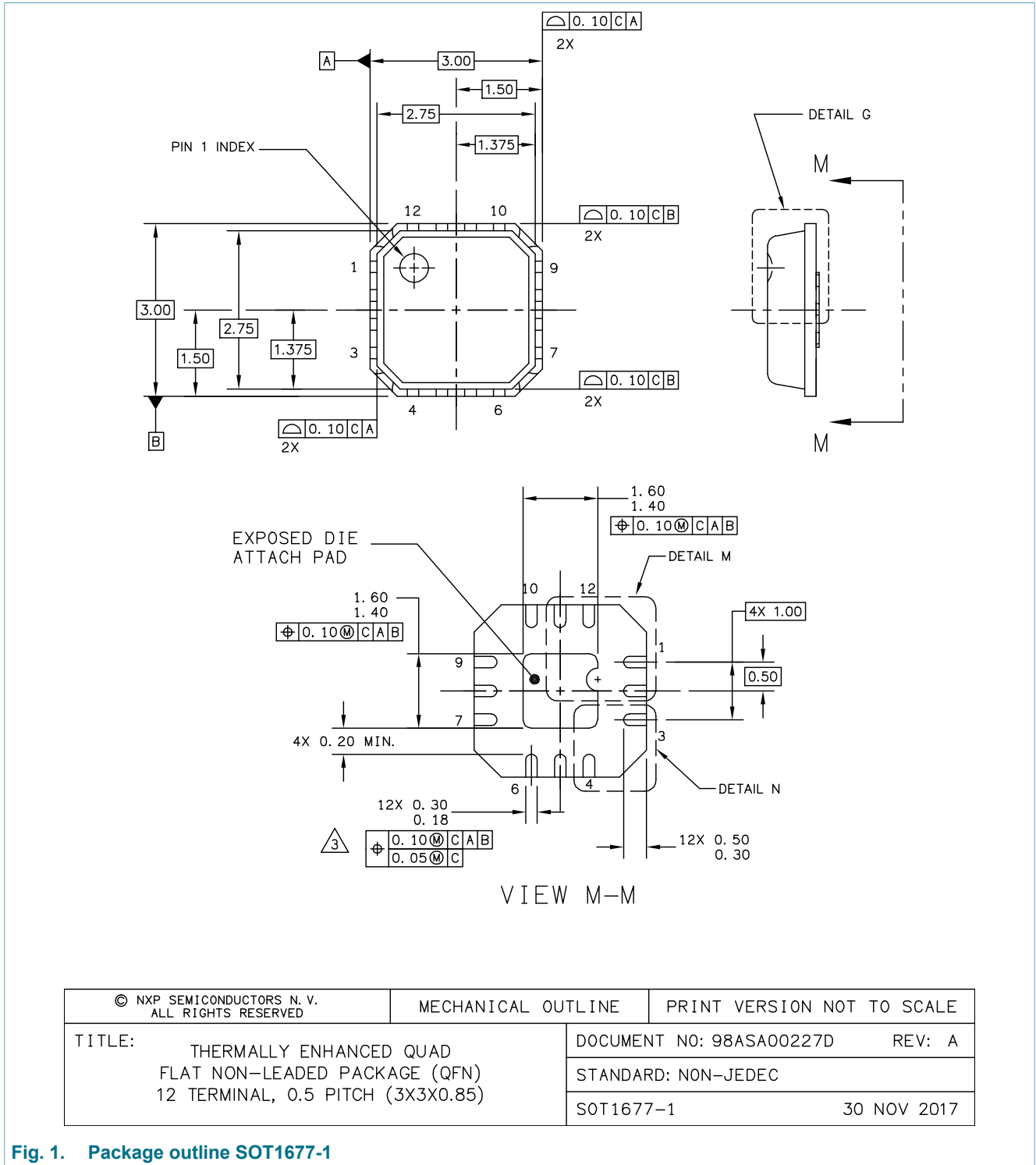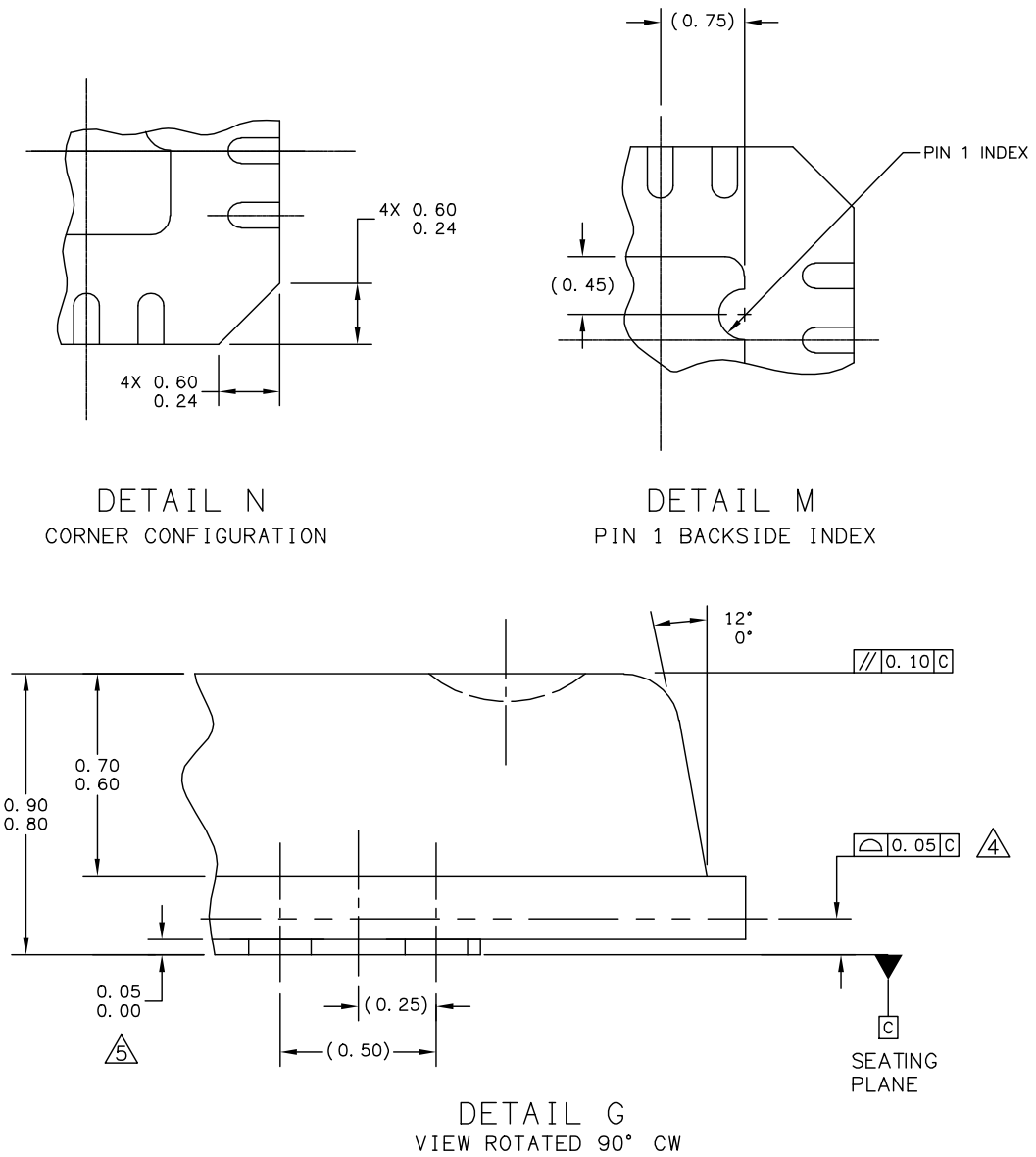| © NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 12 TERMINAL, 0.5 PITCH (3X3X0.85)	DOCUMENT NO: 98ASA00227D	REV: A
	STANDARD: NON-JEDEC	
	SOT1677-1	30 NOV 2017

Fig. 1.   Package outline SOT1677-1

HVQFN12, plastic, thermal enhanced very thin quad flatpack; no leads; 12 terminals; 0.5 mm pitch; 3 mm x 3 mm x 0.85 mm body

DETAIL N
CORNER CONFIGURATION

4X 0.60
0.24

4X 0.60
0.24

DETAIL M
PIN 1 BACKSIDE INDEX

(0.75)

(0.45)

PIN 1 INDEX

12°
0°

// 0.10 C

0.90
0.80

0.70
0.60

0.05 C /4\

0.05
0.00

/5\

(0.25)

(0.50)

C

SEATING
PLANE

DETAIL G
VIEW ROTATED 90° CW

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	SOT1677-1 30 NOV 2017	

Fig. 2.   Package outline dt HVQFN12 (SOT1677-1)

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SOT1677-1

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NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING & TOLERANCING PER ASME Y14.5 − 2009.

3. THIS DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.

4. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

5. THIS DIMENSION APPLIED ONLY FOR TERMINALS.

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	STANDARD: NON−JEDEC	
	SOT1677−1 30 NOV 2017	

Fig. 3.   Package outline note HVQFN12 (SOT1677-1)

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4. Contents

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Package information

21 December 2017

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